

NOTES : (UNLESS SPECIFIED OTHERWISE.)

- 1) ALL DIMENSIONS ARE IN INCHES. TOLERANCE IS  $\pm 0.005$  CONFORMING TO IPC-A-600
- 2) HOLE SIZES ARE SPECIFIED IN THOUSANDTHS.  
HOLE SIZES APPLY AFTER PLATING.  
HOLE SIZE TOLERANCE TO BE  $\pm 0.003$ ,  
UNLESS SPECIFIED OTHERWISE.  
PLATING TO BE 0.0010 MINIMUM.
- 3) MATERIAL : FR-4-2 NATURAL EPOXY/FIBERGLASS  
0.5 OZ. COPPER ALL LAYERS.  
2 SIDES PLATED.  
FINISHED THICKNESS :  $0.047 \pm \frac{0.006}{-0.006}$

- 4) APPLY SOLDERMASK OVER BARE COPPER, BOTH SIDES.  
FINISH ALL EXPOSED COPPER SURFACES WITH 60/40% TIN/LEAD SOLDER, 100u" TO 1000u".
- 5) THE LOCATION OF THE MARKING SHOULD BE ON THE SURFACE OF THE PCB, NOT THE EDGE.
- 6) APPLY SOLDERMASK TO COMPONENT SIDE AND SOLDER SIDE, USING  
☐ PC401 OR EQUIVALENT.  
☒ LIQUID PHOTO IMAGEABLE.  
☐ DRY FILM.  
COLOR : GREEN.  
USE SEPARATE FILM FOR COMPONENT SIDE AND SOLDER SIDE SOLDERMASKS.  
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO SOLDERMASK PHOTO PLOT FILES FOR OPTIMAL SOLDERMASK COVERAGE BETWEEN FINE PITCH COMPONENT LEADS.
- 7) APPLY LEGEND TO TOP SIDE USING NON-CONDUCTIVE EPOXY INK.  
COLOR : WHITE.  
FABRICATOR SHALL MAKE NECESSARY MODIFICATIONS TO LEGEND PHOTO PLOT FILES TO ENSURE NO LEGEND INK COVERS ANY COMPONENT PAD OR VIA PAD.
- 8) PCB SHALL BE CLEAN AND FREE FROM DIRT, OIL, FINGERPRINTS, CORROSION, AND ANY OTHER FOREIGN MATERIAL.
- 9) MODIFIED PHOTO PLOT FILES ARE TO BE RETURNED BEFORE ORDER DELIVERED.
- 10) BOW AND TWIST NOT TO EXCEED 0.005" PER INCH.
- 11) ALL PRINTED CIRCUIT BOARD NETS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS.  
MARK TEXT VERIFICATION STAMP APPROXIMATELY WHERE SHOWN, BOTTOM SIDE.

